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Opinion Statement



Product Carbon Footprint Verification Opinion Statement

This is to verify that: Realtek Semiconductor Corporation
 No. 2, Chuangxin 2nd Rd.
 Baoshan Township
 Hsinchu County 308008
 Taiwan

瑞昱半導體股份有限公司
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308008

Holds Statement No: PCFV 803941

As a result of carrying out the verification and validation procedures in accordance with ISO 14064-3:2019 of product life cycle greenhouse gas emissions, the statement for mixed engagement including reasonable assurance for verification activity and agree-upon procedures (AUP) contains the following:

- The product carbon footprint with the declared unit of Low Power IC (Integrated Circuit) per cubic millimeter and the declared unit of SOC (System-On-Chip) & High throughput IC (Integrated Circuit) per cubic millimeter are verified as in the following table.
- The product life cycle GHG data quality was verified to be acceptable against the requirements of ISO 14067:2018.

This opinion statement shall be valid for a maximum period of two years after the latest issue date on this certificate. Should there be a change in the life cycle of the product whose GHG emissions are being assessed, the validity of this opinion statement will cease.

For and on behalf of BSI:

Managing Director BSI Taiwan, Peter Pu

Originally Registration Date: 2024-05-04

Effective Date: 2024-05-04

Latest Revision Date: 2024-05-04

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Page: 1 of 3

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Taiwan Headquarters: 2nd Floor, No. 37, Ji-Hu Rd., Nei-Hu Dist., Taipei 114, Taiwan, R.O.C.
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The conclusions for different engagement types are explained as follows:

Verification

- Verification are based on reasonable level of assurance.
- The data and information of greenhouse gas emissions are based on historical in nature, and no material misstatements in this product life cycle greenhouse gas emission statement were revealed.

Agreed upon procedures (AUP)

- AUP are specific types of verification activities, BSI have performed the evidence-gathering procedures.
- BSI do not express any assurance on the GHG emissions, removals and storage.

Product Carbon Footprint	Emissions for Each Engagement Types (Unit: gCO ₂ e)		
	Agree-Upon Procedures (AUP)	Verification	
Low Power IC per mm3	6.881	0.148	7.03
SOC & High throughput IC per mm3	3.377	0.148	3.52

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Location	Verification Information
Realtek Semiconductor Corporation No. 2, Chuangxin 2nd Rd. Baoshan Township Hsinchu County 308008 Taiwan 瑞昱半導體股份有限公司 臺灣 新竹縣 寶山鄉 創新二路 2 號 308008	The product carbon footprint with the declared unit of Low Power IC (Integrated Circuit) per cubic millimeter and the declared unit of SOC (System-On-Chip) & High throughput IC (Integrated Circuit) per cubic millimeter are verified as in the following table.

Product related information is as follows:

- System boundary for this product: Cradle to Gate
The product system boundary is consistent with its system boundary definition in the PCF report for product carbon footprint, which involves the acquisition of materials, process activity and the transportation of materials in the product life cycle.
 - The data in this product life cycle greenhouse gas inventory report is from 2023-01-01 to 2023-12-31.
 - The site-specific data include related facilities listed below from its own processes under the operational control of the organization and individual processes under the financial or operational control of the organization undertaking the CFP study.
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|---|--|
| Realtek Semiconductor Corporation, Factory II | No. 9, Yuanqu 2nd Rd., East Dist., Hsinchu Science Park, Hsinchu City 300091, Taiwan |
| Realtek Semiconductor Corporation, Factory III | No. 9-1, Yuanqu 2nd Rd., East Dist., Hsinchu Science Park, Hsinchu City 300091, Taiwan |
| Realtek Semiconductor Coporation, Taipei Office | 2F, No. 126, Lequn 3rd Rd., Zhongshan Dist., Taipei City 104050, Taiwan |
| Realtek Semiconductor Coporation, Tinan Office | No. 11, Nanke 3rd Rd., Xinshi Dist., Tainan City 744094, Taiwan |
- The secondary data include relative factors from EPA Carbon Footprint Calculation Platform and LCA software SimaPro v9.5.0.0 (IPCC 2021 GWP 100a).

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